

PIN FIN HEAT SINK



904 Series

Wakefield-Vette's 900 Series Heat Sinks for Chipset can match up to devices from:

Intel, Broadcom, Xilinx, TI, Motorola, ATI, AMD, Nvidia, Vishay, Powerex, Infineon, Microsemi, and many more.

These heat sinks are designed for air flow applications in the Telecom, Data Center, Networking, Cloud Computing, and many more Industries.

Material: AL 6063

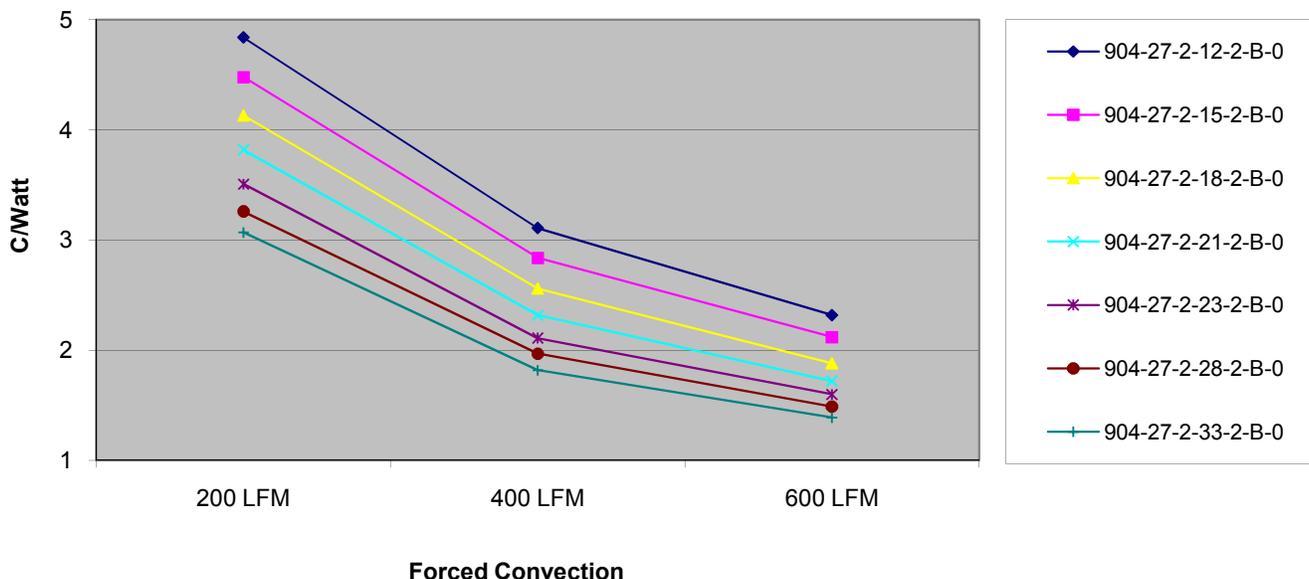


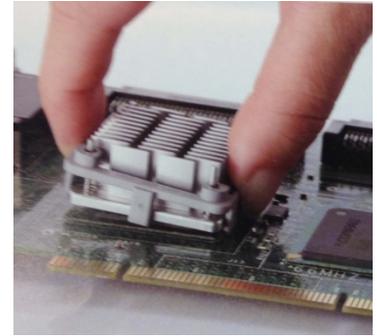
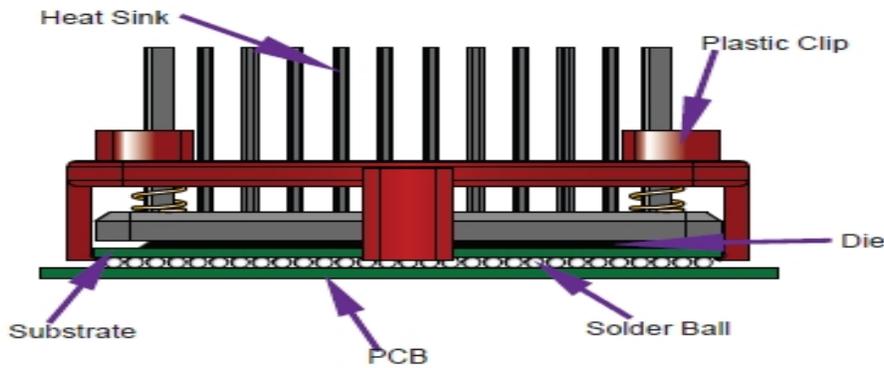
Finish: Black Anodize



PART #	HEIGHT (mm)	CHIP SIZE (mm)	NATURAL CONVECTION	FORCED CONVECTION (C/W)		
				200 LFM	400 LFM	600 LFM
904-27-2-12-2-B-0	12	27	11.38 C/W	4.84 C/W	3.11 C/W	2.32 C/W
904-27-2-15-2-B-0	15	27	10.78 C/W	4.48 C/W	2.84 C/W	2.12 C/W
904-27-2-18-2-B-0	18	27	10.17 C/W	4.13 C/W	2.56 C/W	1.88 C/W
904-27-2-21-2-B-0	21	27	9.56 C/W	3.82 C/W	2.32 C/W	1.72 C/W
904-27-2-23-2-B-0	23	27	9.44 C/W	3.51 C/W	2.11 C/W	1.6 C/W
904-27-2-28-2-B-0	28	27	9.13 C/W	3.26 C/W	1.97 C/W	1.49 C/W
904-27-2-33-2-B-0	33	27	8.82 C/W	3.07 C/W	1.82 C/W	1.39 C/W

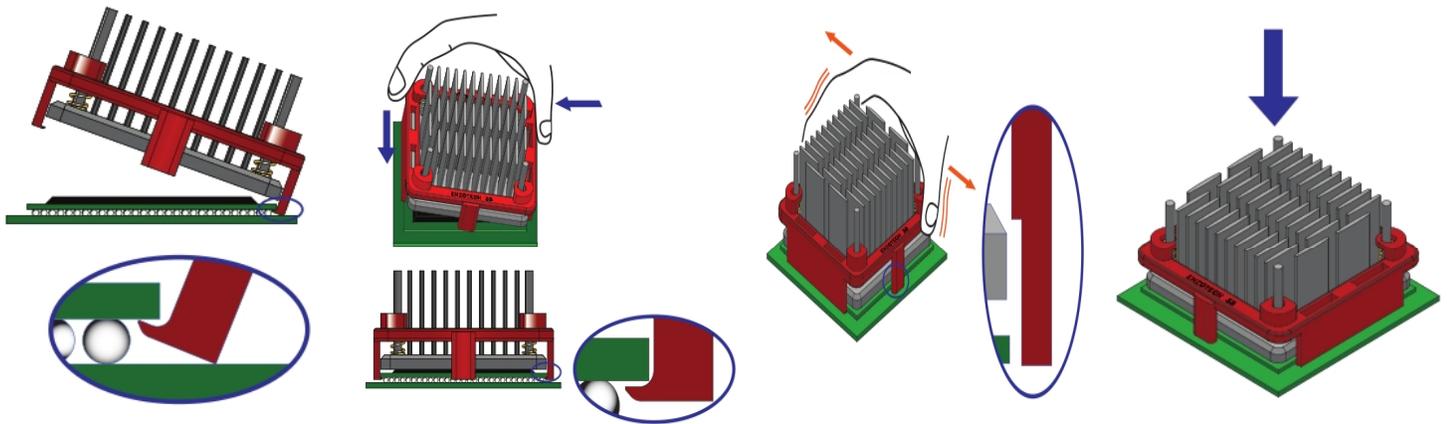
THERMAL PERFORMANCE:





Wakefield-Vette's heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.

ASSEMBLY INSTRUCTION:



Step 1: Hook the clip under one side of the BGA chip set.

Step 2: Rotate assembly down until opposite side clip engages substrate edge of BGA chip set.

Step 3: Make sure the solder rods are clearing from edges of BGA chip set.

Step 4: Press firmly down to make sure clips fully engage edges of chip set. Heat Sink should not move around easily.

Random Vibration Test

Frequency : 5 Hz to 500 Hz
 Acceleration : 3.13 grms
 P.S.D : 0.01 g²/HZ (5 Hz)
 0.02 g²/HZ (20 Hz to 500 Hz)
 Test Axis : X, Y, Z axis
 Test Time : 10 mins (Each axis)
 Total Test Time : 30 mins

SHOCK TEST SPECIFICATION :

Wave Form : Half sine wave
 Acceleration : 50 g
 Duration Time : 11 ms
 No. of Shock : Each axis 3 times
 Shock Direction : ±X, ±Y, ±Z axis
 Reliability & Communication
 Testing Instruments